

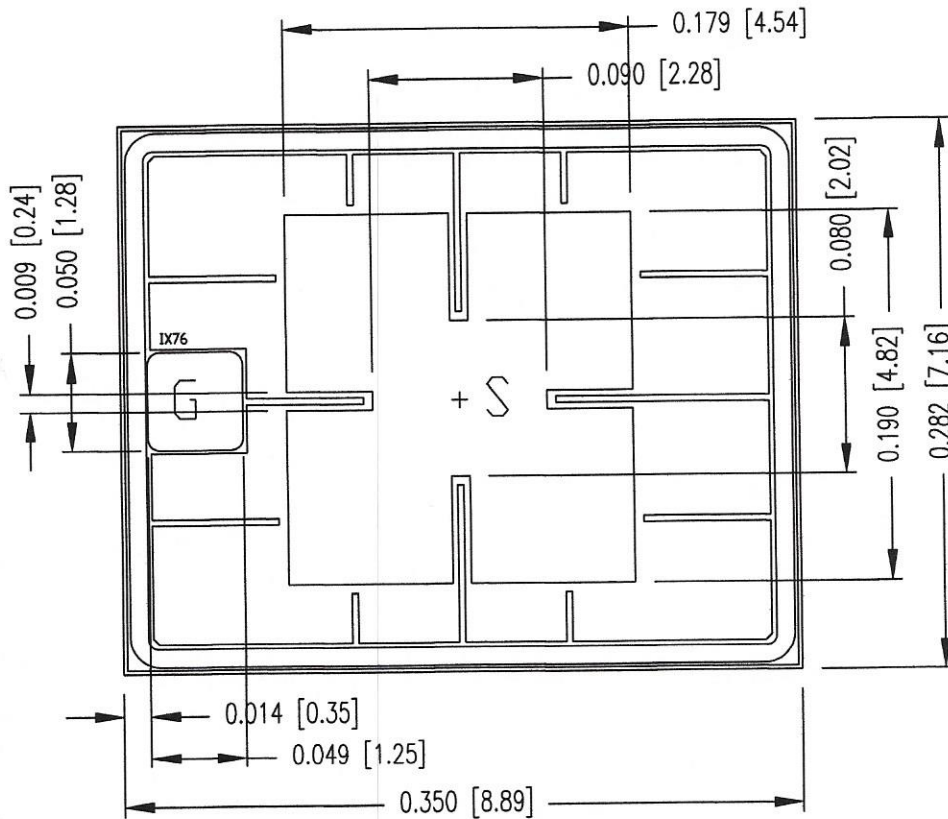


# Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**Top Material: Al**  
**Backside Material: TiNiAg**  
**Bond Pad Size: .090" min.**  
**Backside Potential: Drain**  
**Mask Ref: IX76**

**APPROVED BY: DK**

**DIE SIZE .282" X .350"**

**DATE: 2/26/18**

**MFG: IXYS**

**THICKNESS .008"**

**P/N: IXFD12N120P-76**